



All numerical values are in metric units [with U.S. customary units in brackets]. Dimensions are in millimeters. Unless otherwise specified, dimensions have a tolerance of ± 0.13 mm and angles have a tolerance of $\pm 2^\circ$. Figures and illustrations are for identification only and are not drawn to scale.

1. INTRODUCTION

This specification covers the requirements for application of the zQSFP+ behind bezel cage assembly, heat sink, EMI/dust cover, and light pipe that are used in conjunction with 38-position, 0.8 mm pitch, right-angle surface mount, zQSFP+ connectors used in the communications industry. The cage assembly serves as a housing for the connector and mating transceiver. The cage assembly is a frame with compliant pins for mounting onto the host printed circuit (pc) board. The cage assembly features front perimeter electromagnetic interference (EMI) springs. These springs block any EMI emissions emanating from the transceiver when installed. The cage assembly is designed to be bezel mounted. The front flange provides a flat surface to contact the EMI gasket attached to the perimeter of the bezel cutout. The cage assembly transceiver locking latches hold the transceiver in place, and the hard stop controls the insertion depth of the transceiver.

The EMI/dust cover is used to confine EMI emissions and prevent contaminants from entering the chassis when the transceiver is not installed.

When corresponding with TE Connectivity Personnel, use the terminology provided in this specification to facilitate your inquiries for information. Basic terms and features of this product are provided in Figure 1.

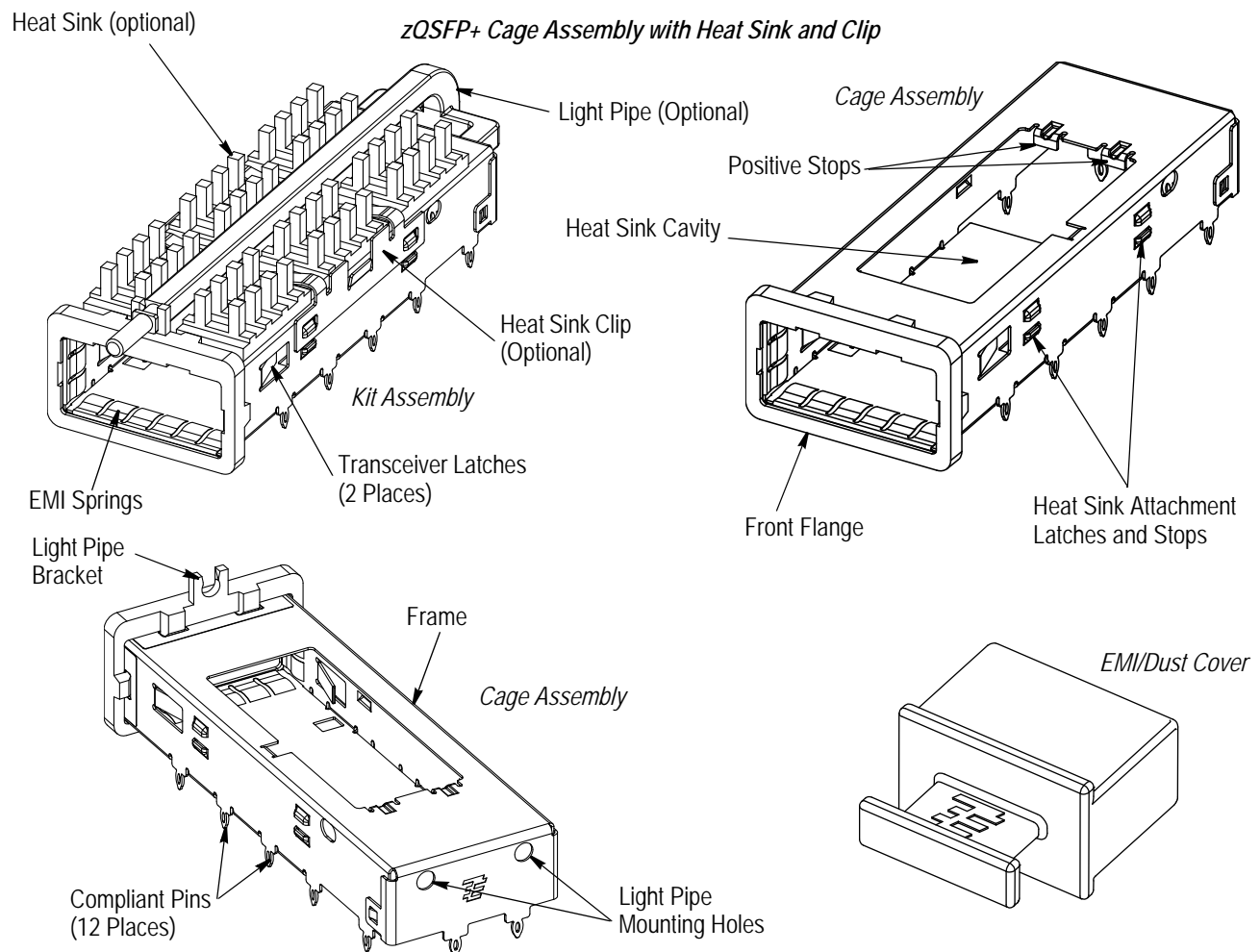


Figure 1 (Cont'd)

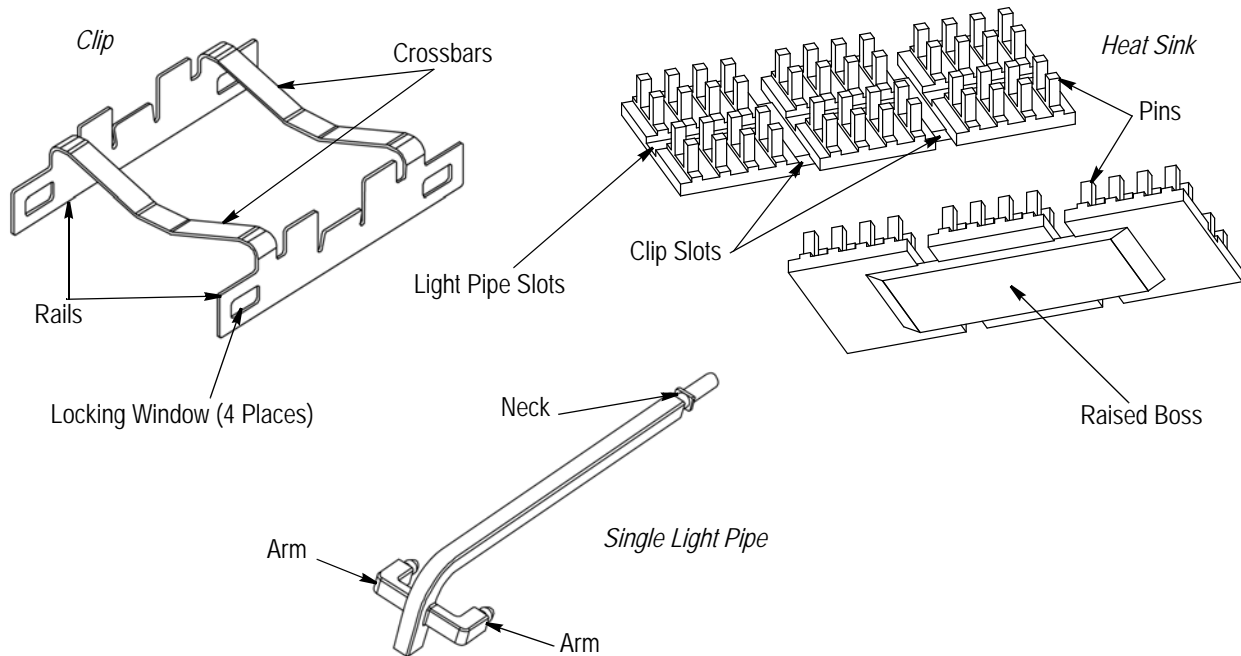


Figure 1 (End)

In applications where heat dissipation is necessary, a heat sink can be used. The heat sink must be chosen to meet the need of the specific application. A sample of available heat sinks are shown in Figure 1. These heat sinks are designed to be attached to the cage assembly using a clip. This type allows insertion and extraction of the transceiver while maintaining the necessary contact between the heat sink and the transceiver. Basic terms and features of this product are provided in Figure 1.

The cage assemblies are available with or without a light pipe. The light pipe is used to transmit light from an LED on the pc board to a panel.

2. REFERENCE MATERIAL

2.1. Revision Summary

- Initial release of document

2.2. Customer Assistance

Reference Product Base Part Numbers 1551891, 1551892, 2173483, 2173484 and Product Code L818 are representative of zQSFP+ Behind Bezel Cage Assemblies. Use of these numbers will identify the product line and expedite your inquiries through a service network established to help you obtain product and tooling information. Such information can be obtained through a local Representative or, after purchase, by calling PRODUCT INFORMATION at the number at the bottom of page 1.

2.3. Drawings

Customer Drawings for product part numbers are available from the service network. If there is a conflict between the information contained in the Customer Drawings and this specification or with any other technical documentation supplied, the information contained in the Customer Drawings takes priority.

2.4. Specifications

Design Objective 108-19428 provides expected product performance and test information.

2.5. Instructional Material

Instruction Sheets (408-series) provide product assembly instructions or tool setup and operation procedures. Documents available which pertain to this product are:

408-32021 zQSFP+ Connector, Behind Bezel Cage Assembly, Heat Sink, and Light Pipe

3. REQUIREMENTS

3.1. Safety

Do not stack component packages so high that the shipping containers buckle or deform.

3.2. Limitations

A. Transceiver Module

The top surface of the Transceiver Module is to be free of EMI bumps and maintain a flatness of 0.08 mm. The width of the mating transceiver module (outside of the cage assembly) cannot exceed 19 mm in order to prevent interference between transceivers inserted into adjacent ports.

B. Bezel

The bezel requirements given in this document are specifically configured for products used in the communications industry, and peripheral component interconnect (PCI) applications.

3.3. Material

The cage assembly frame is made of nickel silver alloy. The EMI springs are made from copper alloy plated with tin. The EMI/dust cover and front flange are made of zinc plated with tin over nickel. The heat sinks are made of nickel-plated aluminum. The heat sink clip is made of stainless steel. The light pipes are made of clear polycarbonate.

3.4. Storage

The cage assemblies should remain in the shipping containers until ready for use to prevent deformation to the contacts and compliant pins. The cage assemblies should be used on a first in, first out basis to avoid storage contamination that could adversely affect performance.

3.5. Chemical Exposure

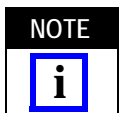
Do not store cage assemblies or accessories near any chemical listed below as they may cause stress corrosion cracking in the contacts or compliant pins.

Alkalies	Ammonia	Citrates	Phosphates	Citrates	Sulfur Compounds
Amines	Carbonates	Nitrites	Sulfur	Nitrites	Tartrates

3.6. Host PC Board

A. Material and Thickness

The host pc board material shall be glass epoxy (FR-4 or G-10). The pc board thickness shall be a minimum of 1.44 mm for mounting the cage assembly to one side of the pc board, and the pc board thickness must be 2.2 mm minimum when mounting the cage assembly to both sides of the pc board.



Contact *PRODUCT INFORMATION* at the number listed at the bottom of page 1 for suitability of other pc board materials.

B. Tolerance

Maximum allowable bow of the pc board shall be 0.08 mm over the length of the cage assembly. The coplanarity of the pc board circuit pads must be 0.03 mm.

C. Circuit Pads

The circuit pads must be solderable in accordance with EIA-364-52.

D. PC Board Layout

All holes and circuit pads must be precisely located on the pc board to ensure proper placement and optimum performance of the connector and cage assembly. Recommended circuit pad pattern, dimensions, and tolerances are provided in Figure 2.

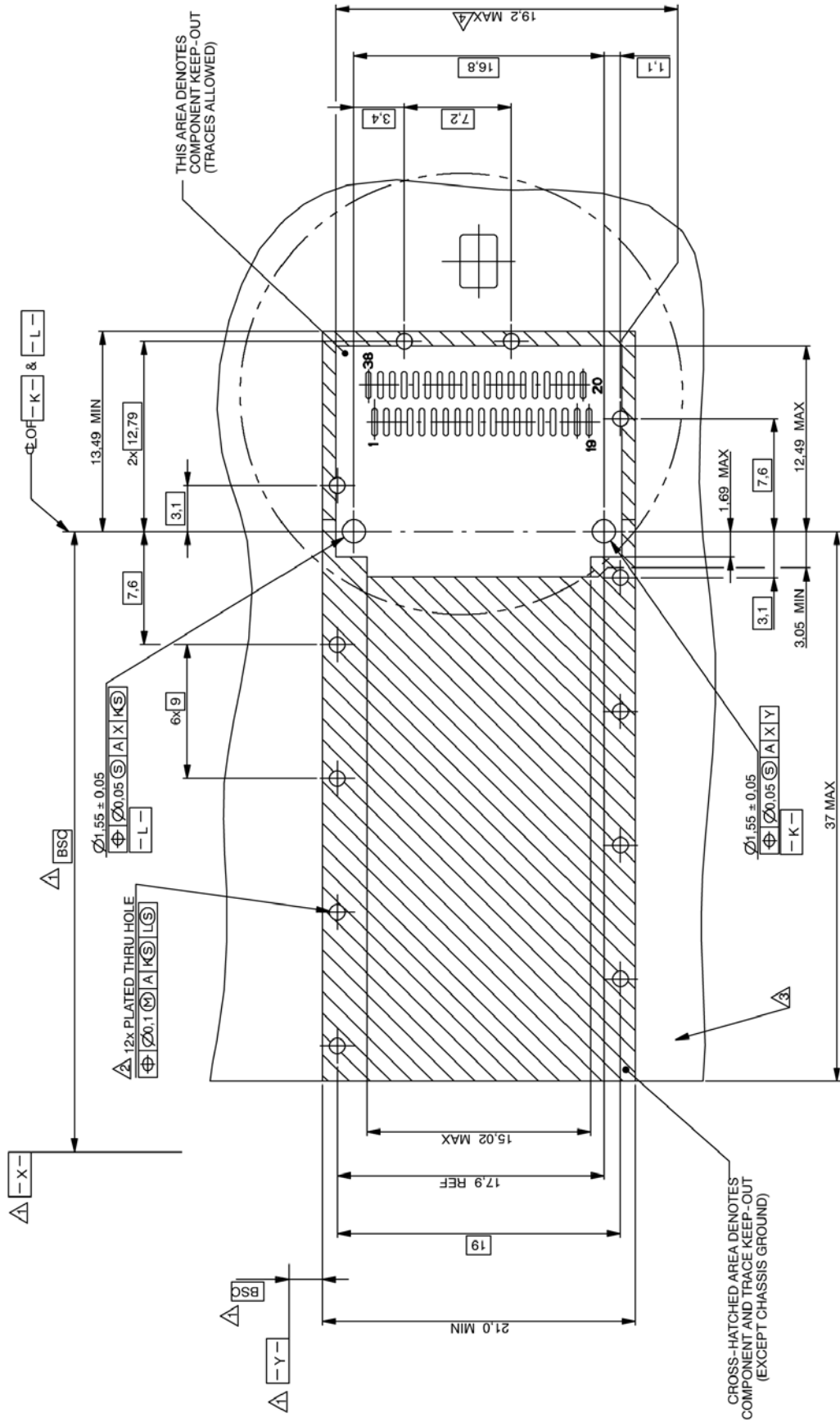
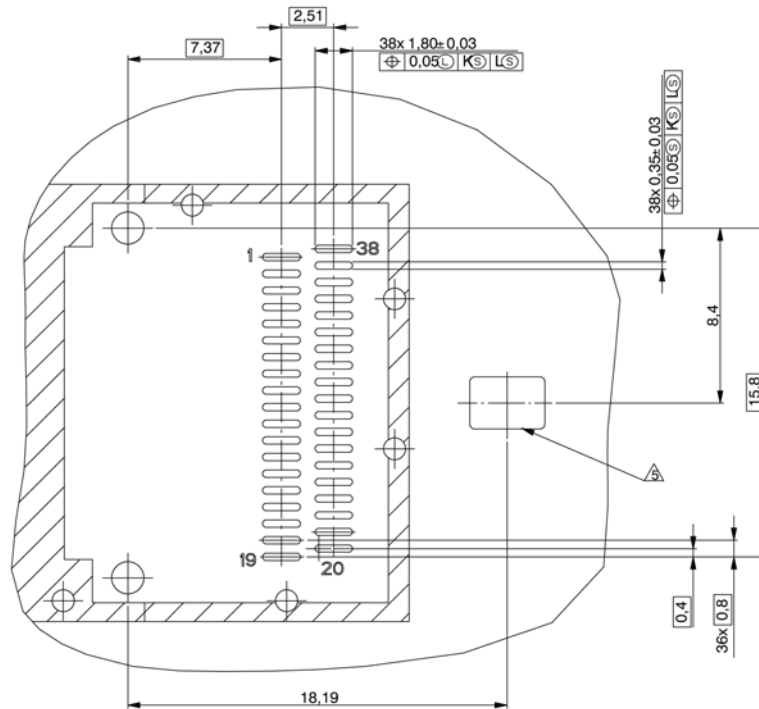


Figure 2 (Cont'd)

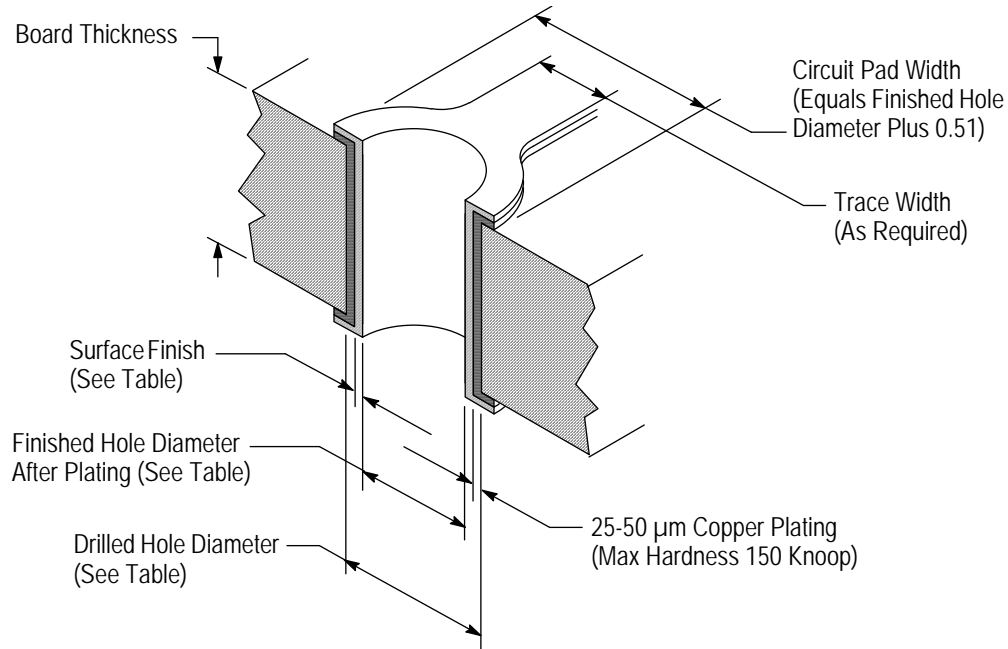


- 1. DATUM AND BASIC DIMENSIONS ESTABLISHED BY CUSTOMER.
- 2. PADS AND VIAS AND CHASSIS GROUND, REFER TO FIGURE 3 FOR HOLE SIZES AND PLATING SPECIFICATIONS.
- 3. DATUM \square -A- IS TOP SURFACE OF PC BOARD.
- 4. SURFACE TRACES PERMITTED WITHIN THIS LENGTH.
- 5. AREA OF THE PC BOARD COVERED BY INPUT AREA OF OPTIONAL SINGLE LIGHT PIPE 2173481-1, DIMENSIONS INDICATE RECOMMENDED CENTER OF LED.

Figure 2 (End)

E. Hole Dimensions

The contact alignment post holes and cage assembly compliant pin holes must be drilled and plated through to specific dimensions to prevent stubbing during placement of the connector and cage assembly on the pc board. The drilled hole size, plating types, and plating thickness are dependent on the application requirements. The finished hole size must be as stated to provide unrestricted insertion. See Figure 3.



DRILLED HOLE DIAMETER	FINISHED HOLE DIAMETER	SURFACE FINISH	
		MATERIAL	THICKNESS
1.15 ±0.02	1.05 Ref	HASL SnPb	0.004-0.010
		Immersion Sn	0.0005 Min
		OSP	0.0002-0.0005
		Immersion Au/Ni	0.004-0.0076/0.0001-0.0005

Figure 3

3.7. EMI Gasket

It is recommended that a gasket be installed onto the back of the bezel for EMI suppression (between the cage assembly and the bezel). The design and material of the gasket can be specific to the application, but must cover the perimeter of the bezel cutout. The gasket can be attached to the bezel using a pressure-sensitive adhesive. There must be no gap between the gasket and the bezel.

When the cage assembly (with the host pc board) is mounted onto the bezel, the gasket must be compressed to the recommended thickness specified by the manufacturer of the gasket. The thickness of the gasket can be determined by the following calculation:

$$GT = BKL - 42 \text{ mm} + 0.25 \text{ mm}$$

GT = thickness of compressed gasket

BKL = distance between back of bezel to the centerlines of datums K and L (see Figure 2)

The distance between the front of the bezel to datums K and L must not exceed 48 mm

3.8. Bezel

A. Thickness

The bezel thickness range shall be 0.8 mm through 2.6 mm.

B. Cutout

The bezel must provide a cutout that allows proper mounting of the cage assembly. Care must be used to avoid interference between adjacent cage assemblies and other components. The minimum allowable distance between cage assemblies must be considered to ensure proper assembly. Dimensions for bezel cutout and minimum allowable distance between cutouts are shown in Figure 4.

C. Bezel Position

The bezel and host pc board must be positioned in relation to each other to avoid interference with the insertion and extraction of the transceiver. This relationship must conform to the dimensions given in Figure 4.

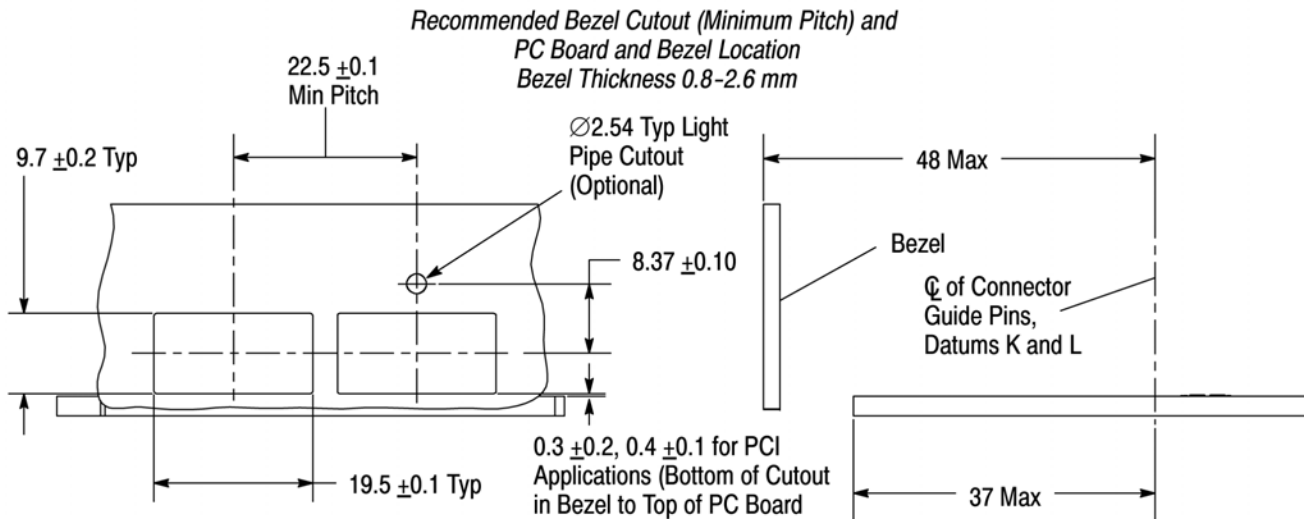
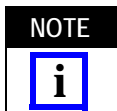


Figure 4

3.9. Cage Assembly Placement



The connector must be soldered to the pc board BEFORE seating the cage.

A. Registration

The compliant pin contacts must be aligned with matching holes in the pc board, then inserted into the pc board simultaneously to prevent twisting or bending of these parts.

B. Seating



A customer supplied pc board support fixture must be used to provide proper support for the host pc board, and to prevent damage to the host pc board and adjacent components. Refer to Section 5 for design requirements.

Using proper seating force and seating height is essential to interconnection performance. The force used to seat the cage assembly must be applied evenly to prevent deformation or other damage to the compliant pin contacts. The force required to seat the cage assembly onto the pc board can be calculated by:

Amount of Compliant Pin Contacts X 44.5 N [10 lbs] (Force per Compliant Pin Contact) = Seating Force



Over-driving the cage assembly will deform parts critical to the quality of the connection. Maximum force occurs prior to the cage assembly bottoming on the pc board.

When using tooling to seat the cage assembly, the shut height of the application tool must be specifically set for proper seating of the cage assembly. The shut height can be calculated by:

$$\text{Seating Height (Cage Assembly Seated)} + \text{Height of Seating Tool} + \text{Combined Thickness of PC Board and PCB Support Fixture} = \text{Shut Height (Ram Down)}$$



The shut height may need to be adjusted to maintain the 0.10 mm maximum gap dimension between the standoffs of the cage assembly and the pc board.

The cage assembly must be seated on the pc board not exceeding the dimensions shown in Figure 5.

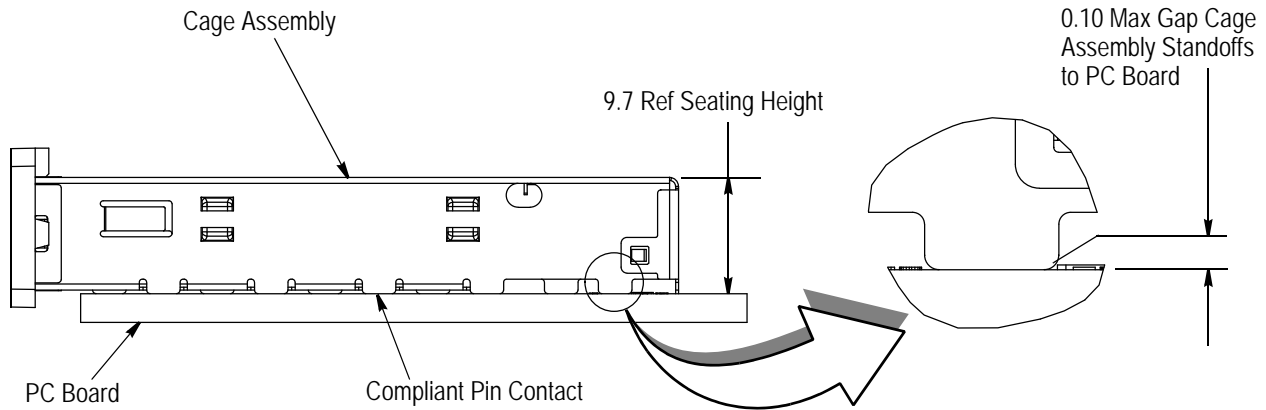


Figure 5

3.10. Checking Installed Cage Assembly

After installation, the EMI gasket supplied by the customer must be compressed around its entire perimeter by the front flange of the cage assembly. A slight bow in the cage is permitted. The bezel and pc board must be positioned according to the dimensions shown in Figure 6.

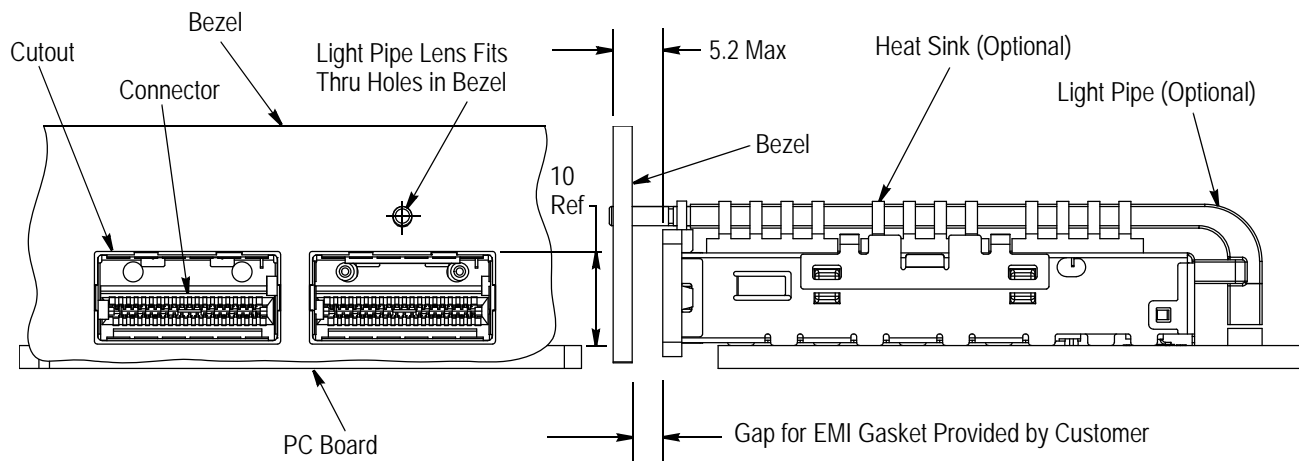


Figure 6

3.11. Heat Sink and Clip

The heat sink must be placed on the cage assembly and secured to the cage assembly using the clip. After the heat sink and clip are installed, the following requirements must apply (refer to Figure 7):

- The perimeter of the heat sink must be flush with the top of the frame of the cage assembly

- The raised boss must be centered in the cavity of the cage assembly
 - The clip locking windows must be fully latched onto the cage locking latches of the cage assembly
- Any heat sink used must be flush with and securely attached to the cage assembly.

NOTE: For Clarity, Connector, PC Board, and Bezel are Not Shown

Perimeter of Heat Sink
Rest on Cage Frame

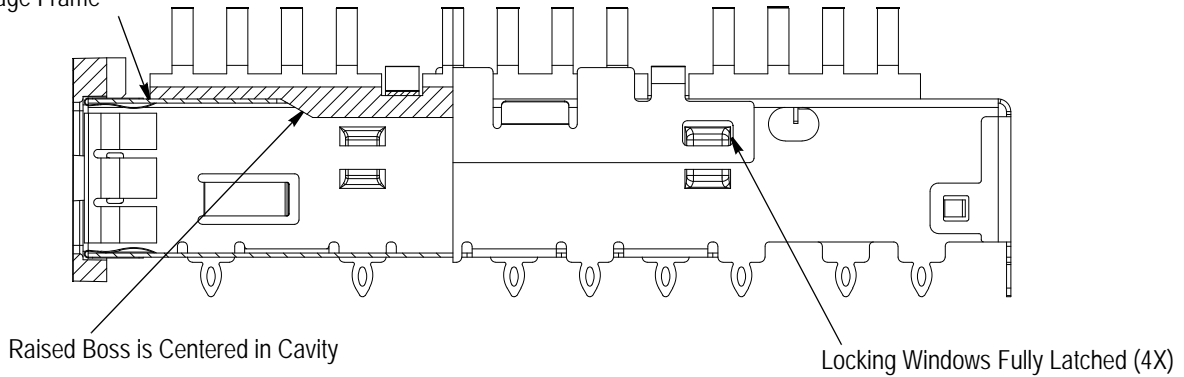


Figure 7

3.12. Dust Cover

A dust cover must be installed into the port when the module is not mated with the cage assembly.

3.13. Light Pipe

A light pipe may be installed on various zQSFP+ cage assemblies. They can be used either with or without the appropriate heat sink, but must be installed after the heat sink and heat sink clip if these items are being used. Contact PRODUCT INFORMATION at the bottom of page 1 for combinations of heat sinks and light pipes.

The bezel must have an additional cut-out for each port on which a light pipe will be installed. See Figure 4 for placement of these cut-outs. The appropriate location of the LED's on the host pc board is provided in Figure 2.

When the light pipe is installed, both arms of the light pipe must be latched into the mounting holes on the rear of the cage assembly. The front of the light pipe must be latched into the light pipe bracket on the front of the cage.

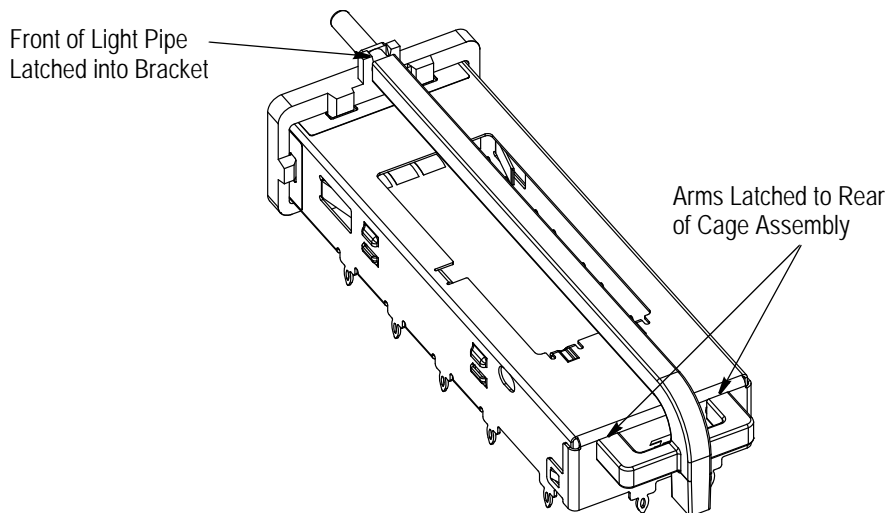


Figure 8

3.14. Removal and Repair

The optional light pipe can be removed by first lifting the front end of the light pipe out of the light pipe bracket on the front of the cage assembly. Then apply pressure to the outside of the arms of the light pipe, pressing them toward each other while gently pulling the light pipe back from the rear of the cage. As long as the light pipe is not cracked or warped, it can be re-used on any thru bezel cage assembly that has a light pipe bracket.

The clip (that secures the heat sink) must be removed using a tool (such as a small screwdriver or hobby knife) according to the following:

1. Insert the tip of the tool into either release aperture of the clip, and rotate the tool until the corresponding locking windows are released from the cage locking latches of the cage assembly. Repeat this step for the remaining release aperture. See Section 6.
2. Lift the clip and heat sink from the cage assembly.



The heat sink must be removed from the cage assembly before removing the cage assembly from the host pc board. A flat metal bar (or similar object) can be partially inserted into the front of the cage assembly (the object MUST NOT touch the connector; otherwise, damage to the contacts could occur). The cage assembly can then be removed by lifting it off the pc board. The cage assembly MUST NOT be re-used after removal.



The cage assembly must be removed from the host pc board before removing the connector. Standard de-soldering methods must be used to remove the connector from the host pc board. The connector MUST NOT be re-used after removal. The connector and cage assembly are not repairable. Any defective or damaged products MUST NOT be re-used.

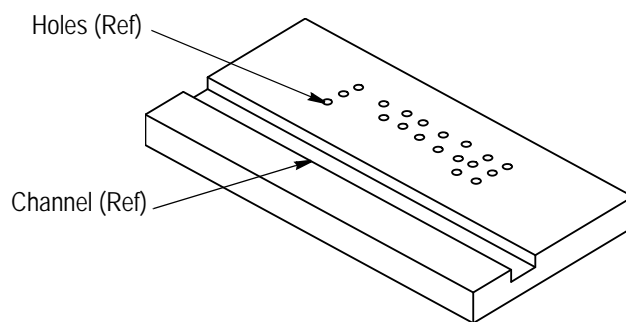
4. QUALIFICATIONS

No qualifying support for zQSFP+ connectors was defined at the time of publication of this document.

5. TOOLING

No tooling is required for manual placement of the cage assembly onto the pc board. For placement of a single zQSFP+ cage assembly onto the host pc board, flat rock tooling may be used. Tooling is available for seating and removing a ganged cage assembly.

A pc board support fixture must be used to provide proper support for the host pc board, and to prevent damage to the host pc board and its adjacent components during seating of the cage assembly. It must have a flat surface with holes or a channel wide and deep enough to receive any protruding components during seating of the cage assembly on the host pc board. See Figure 9.



*PC Board Support Fixture
(Application Specific, Customer Supplied)*

NOTE: The customer designed pc board support should be designed using the pc board layout from the specific customer print.

Figure 9

6. VISUAL AID

The illustration below shows a typical application of this product. This illustration should be used by production personnel to ensure a correctly applied product. Applications which DO NOT appear correct should be inspected using the information in the preceding pages of this specification and in the instructional material shipped with the product or tooling.

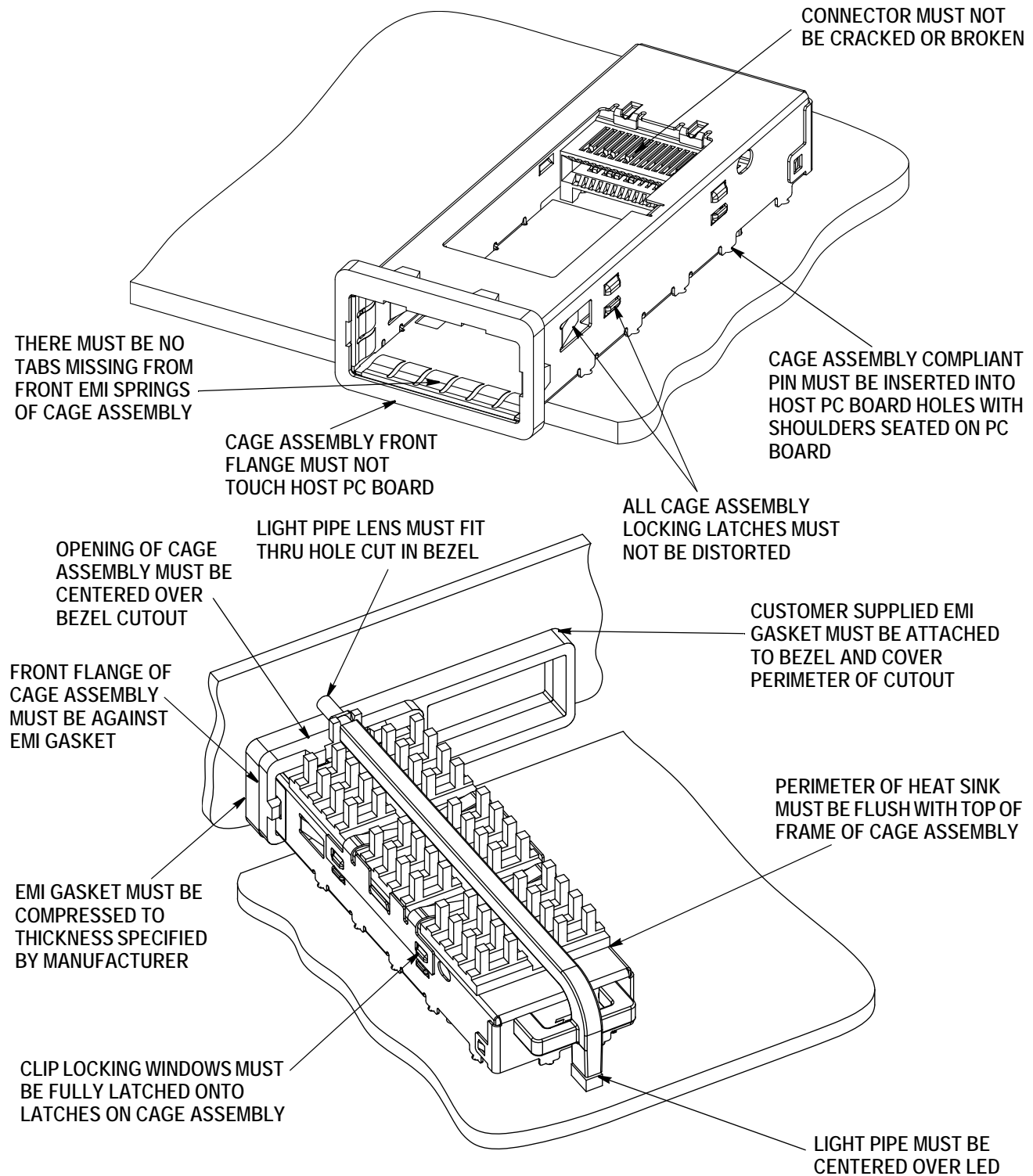


FIGURE 10. VISUAL AID